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(54) **ULTRASOUND TRANSDUCER,
ULTRASOUND PROBE AND METHOD OF
MANUFACTURING ULTRASOUND
TRANSDUCER**

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(71) Applicant: **OLYMPUS CORPORATION**, Tokyo
(JP)

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(72) Inventor: **Katsuhiko WAKABAYASHI**, Tokyo
(JP)

(73) Assignee: **OLYMPUS CORPORATION**, Tokyo
(JP)

(57) **ABSTRACT**

(21) Appl. No.: **15/788,925**

An ultrasound transducer includes: piezoelectric elements; a substrate configured to perform input and output of an electric signal with respect to each of the piezoelectric elements; signal input and output electrodes where each signal input and output electrode is provided between each piezoelectric element and the substrate; first backing materials where each first backing material is provided at each of the piezoelectric elements on a side where the signal input and output electrode is arranged; sealing portions where each sealing portion is configured to seal an outer surface of at least a portion of an electrical path connecting the substrate with the signal input and output electrode; a wall configured to surround oscillating portions including the piezoelectric element, the first backing material, the signal input and output electrode, and the sealing portion; and a second backing material provided in a hollow space formed by the wall and the oscillating portions.

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(30) **Foreign Application Priority Data**

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H04R 31/00 (2006.01)

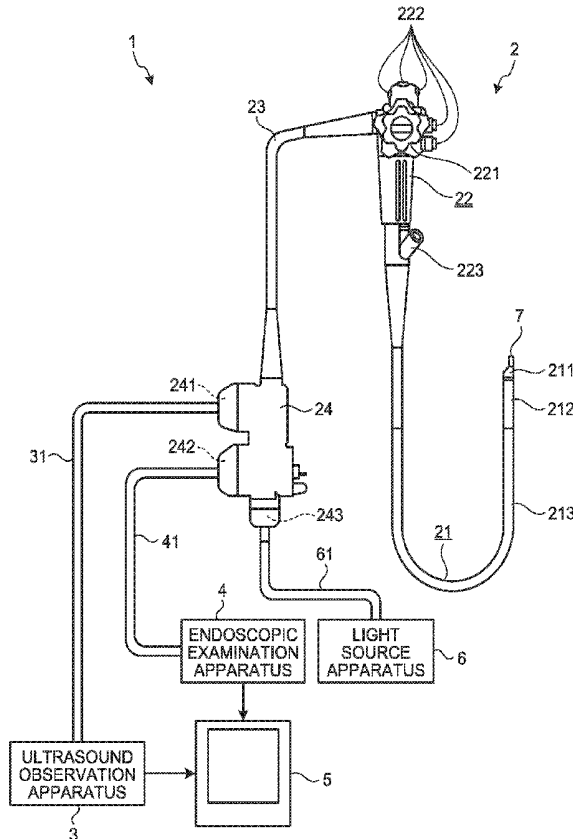


FIG.1

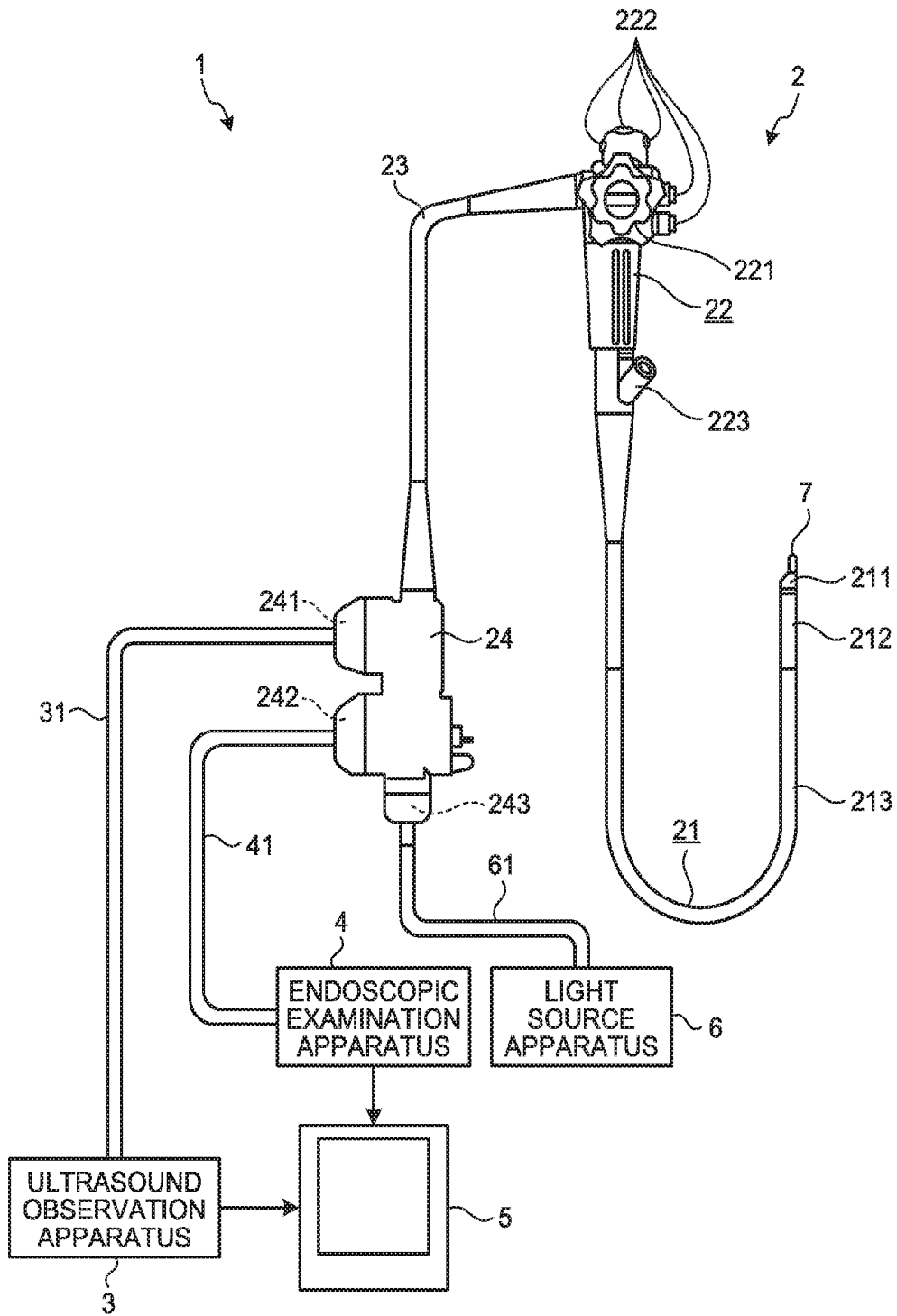


FIG.2

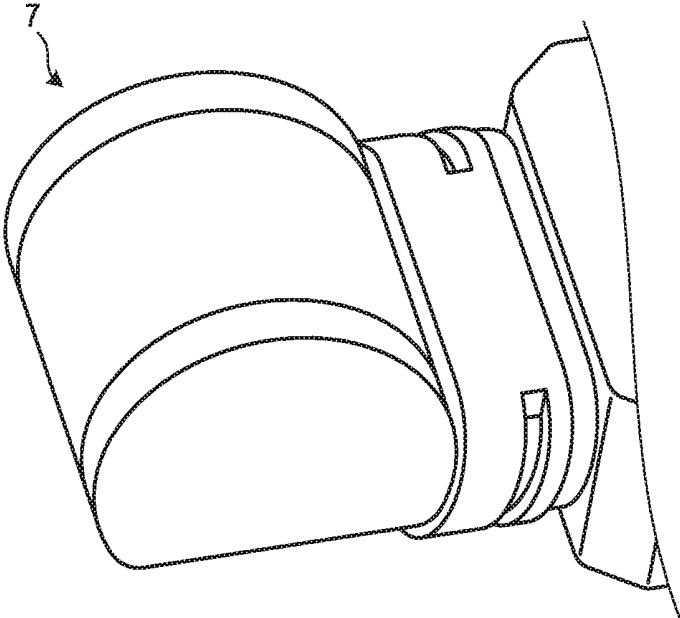


FIG.3

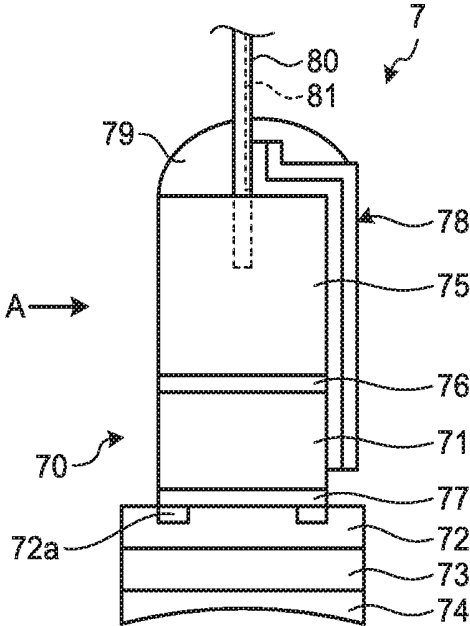


FIG.6

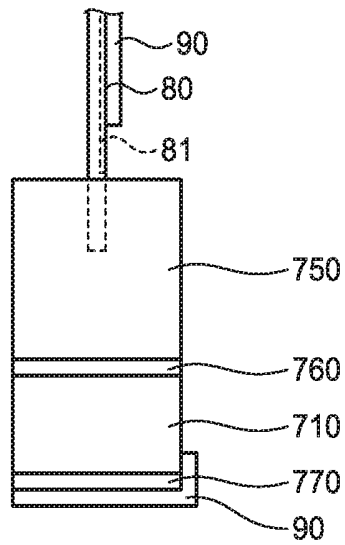


FIG.7

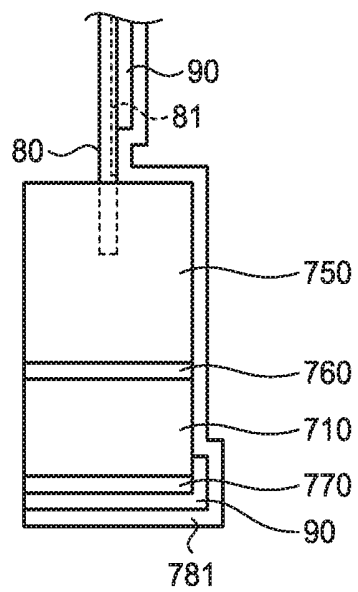


FIG.8

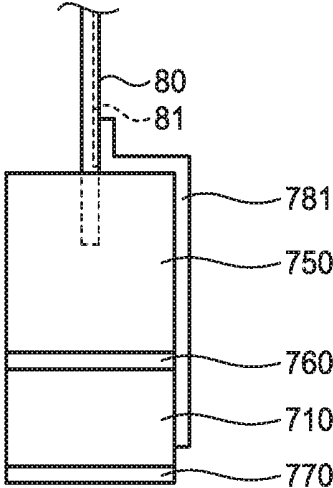


FIG.9

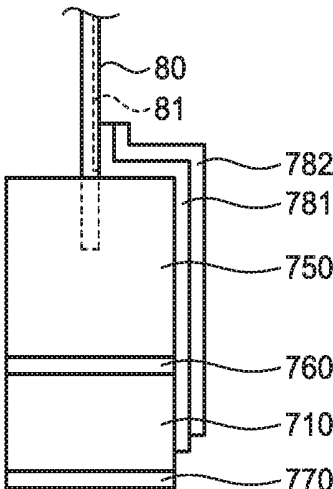


FIG.10

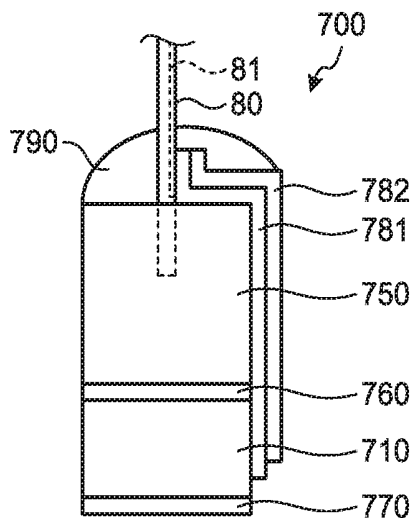


FIG.11

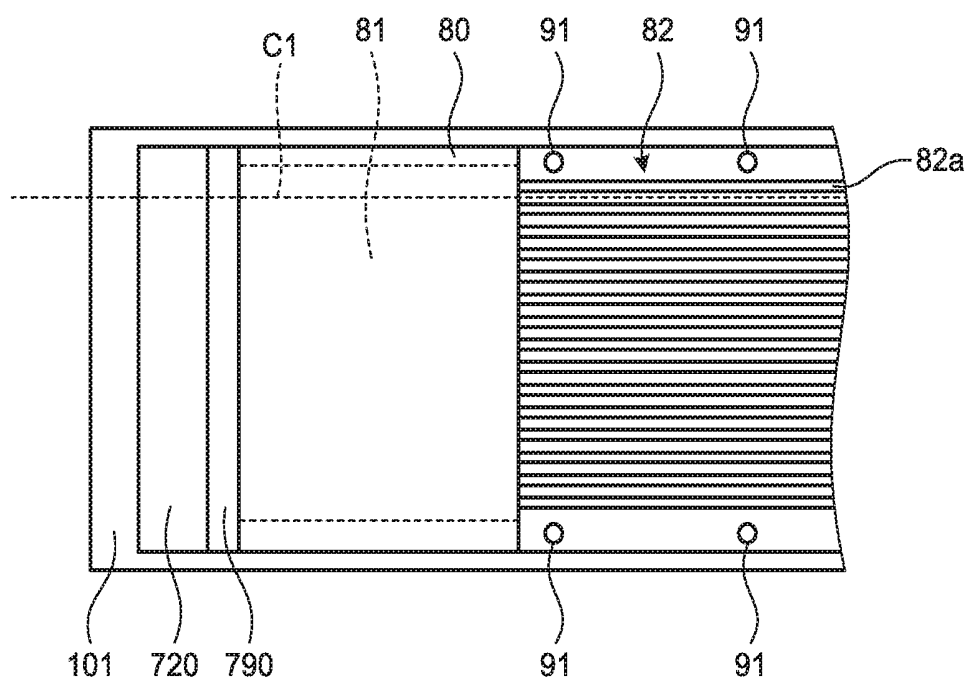


FIG.12

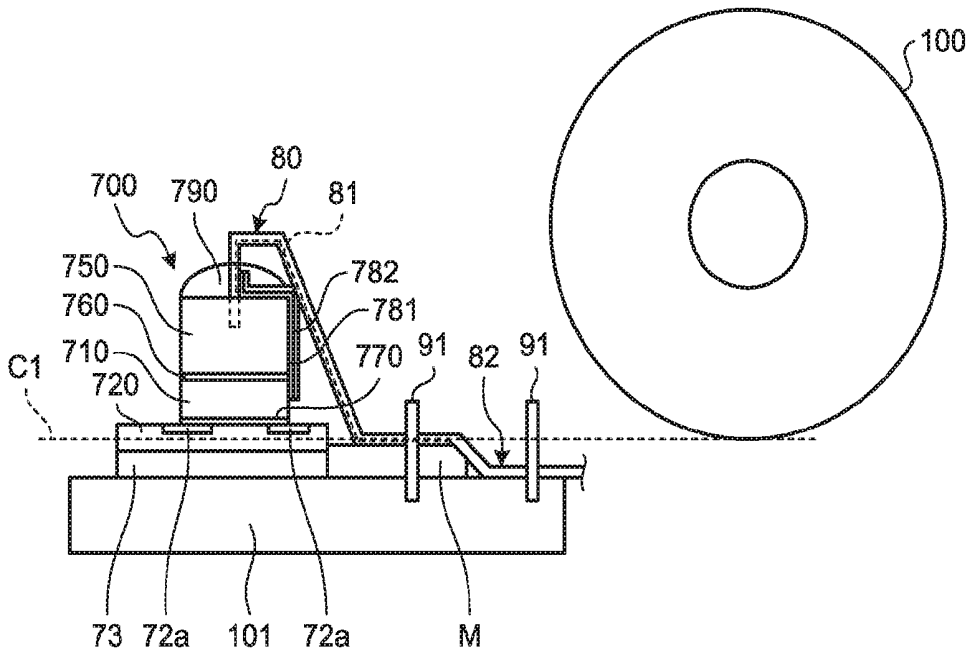


FIG.13

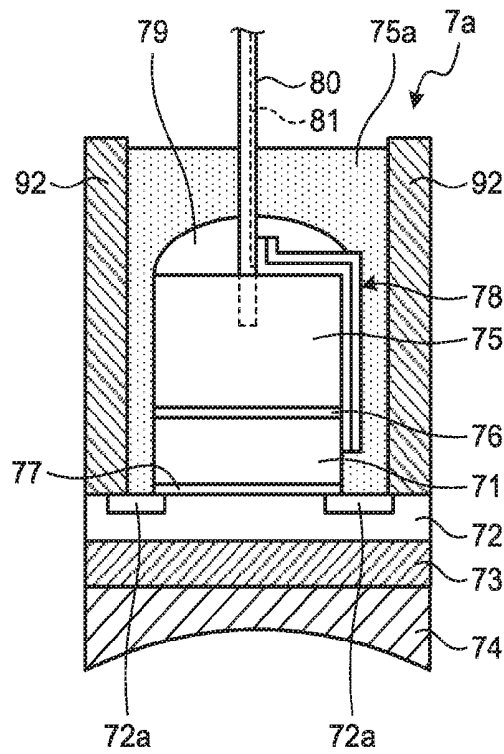


FIG. 14

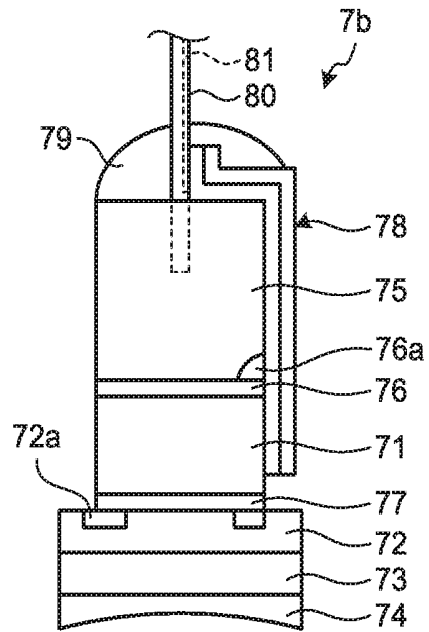


FIG. 15

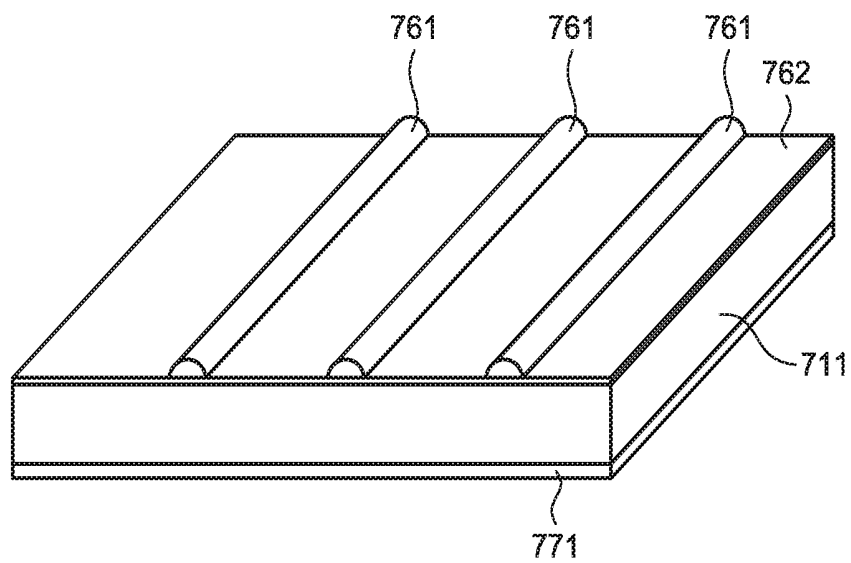


FIG.16

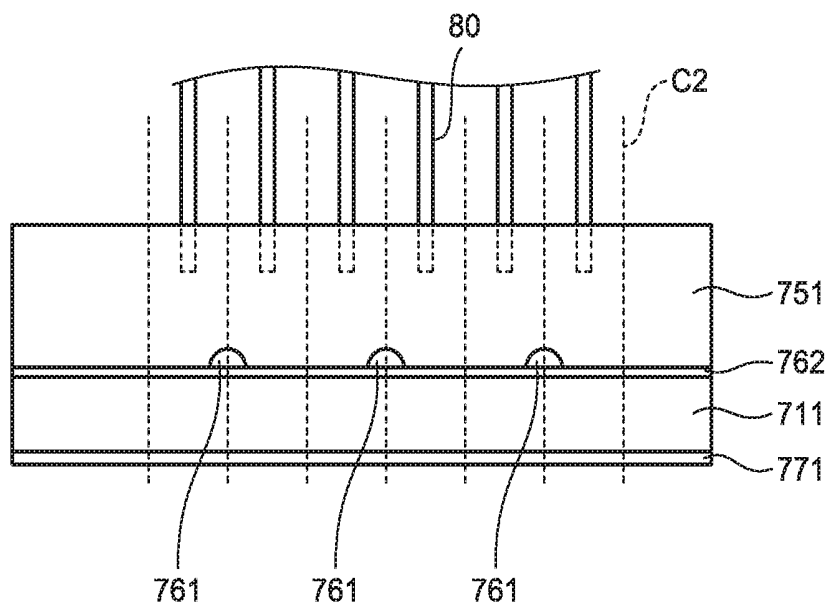


FIG.17

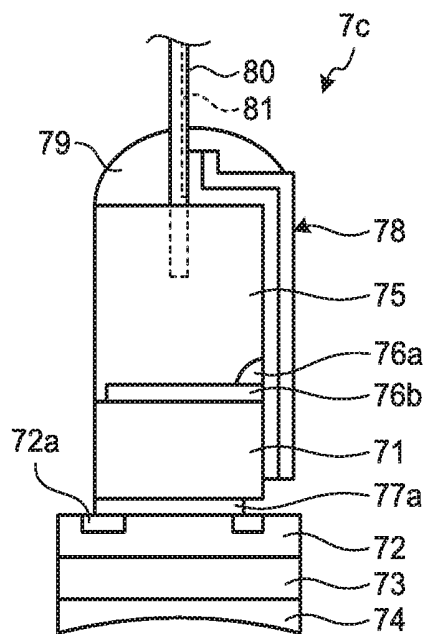


FIG.18

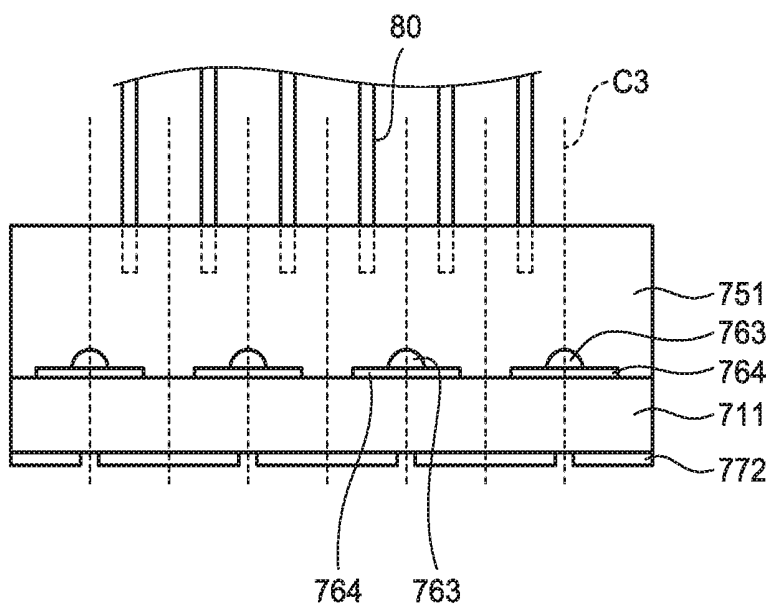


FIG.19

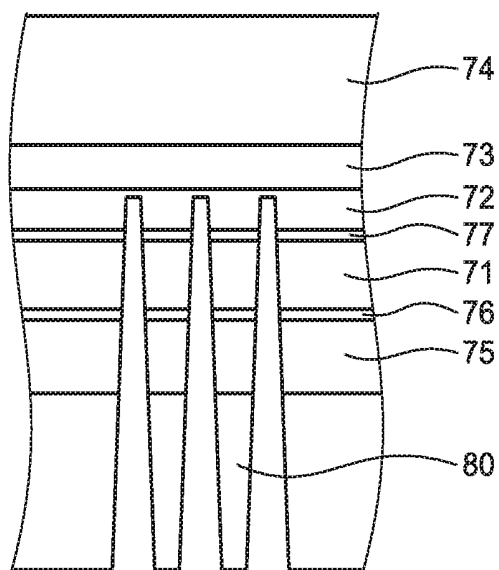


FIG.20

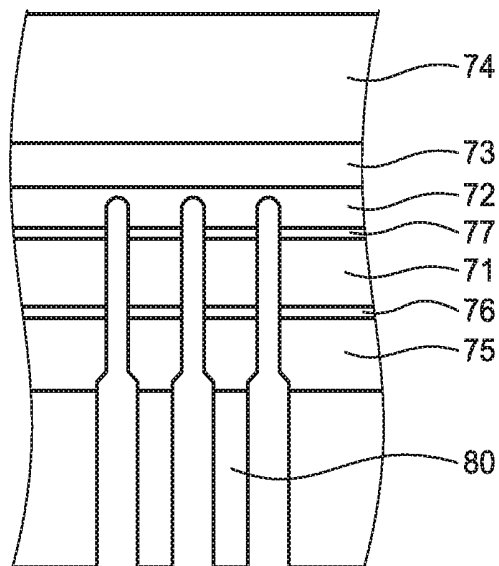


FIG.21

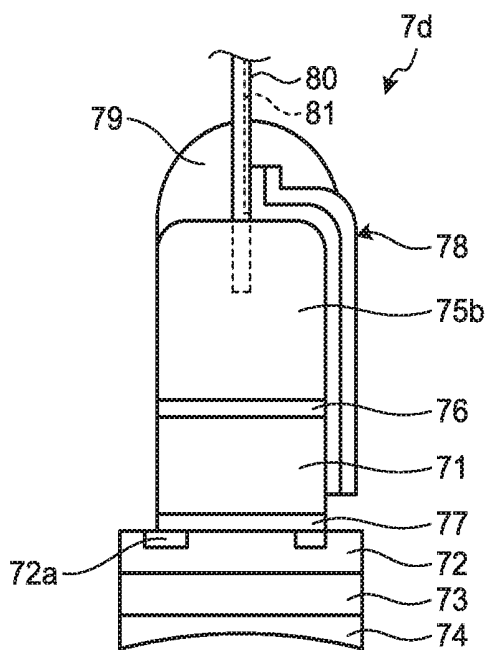


FIG.22

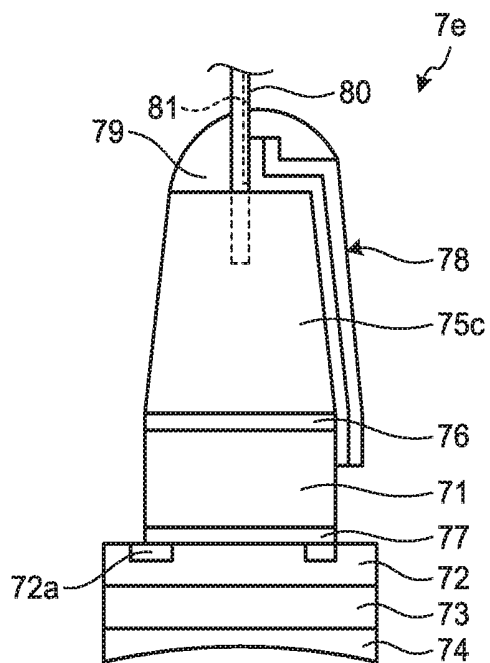


FIG.23

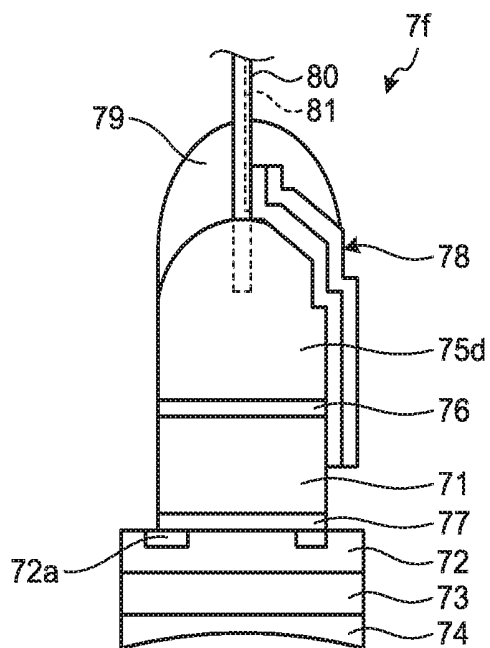


FIG.24

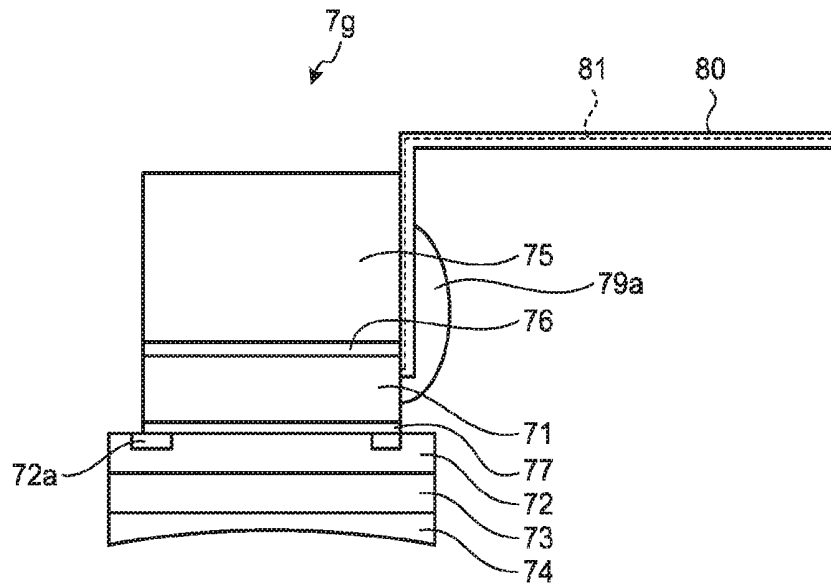


FIG.25

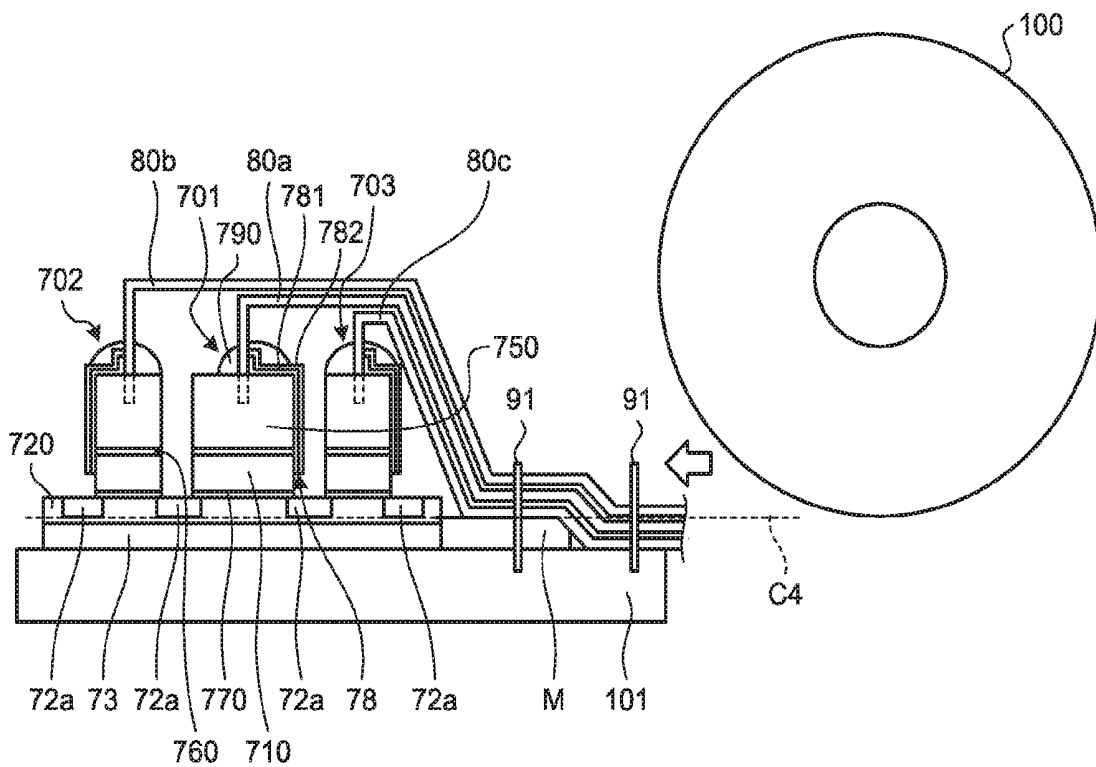


FIG.26

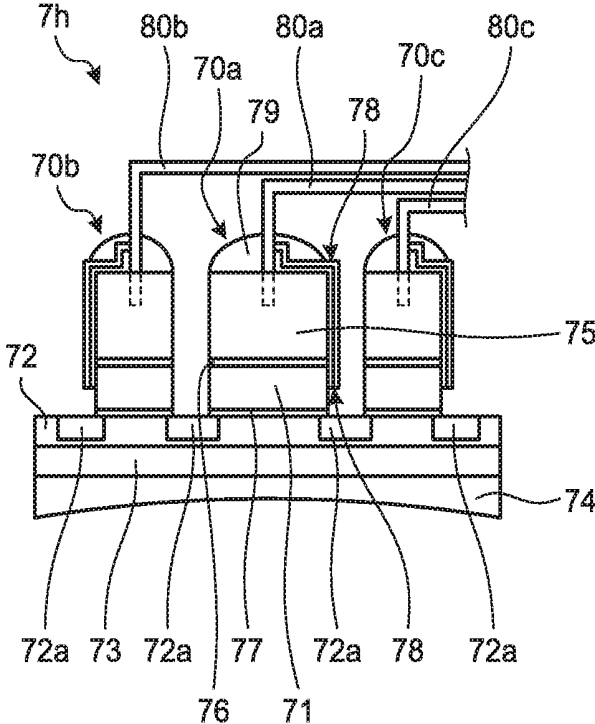


FIG.27

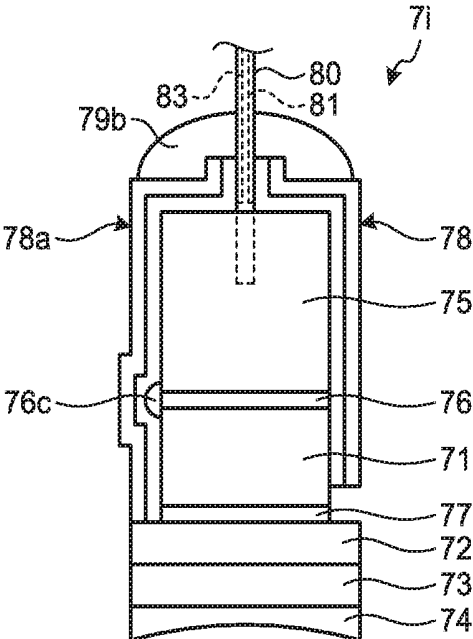


FIG.28

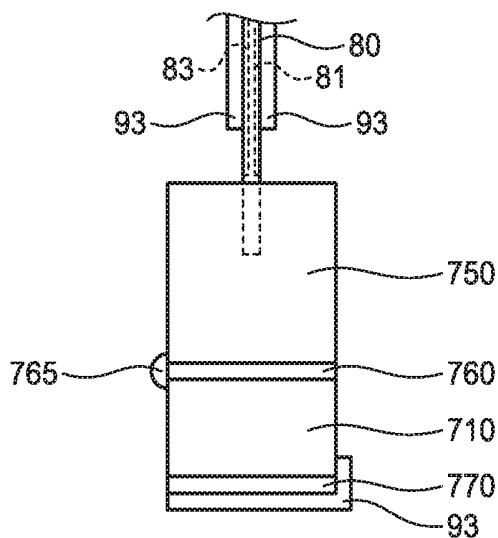


FIG.29

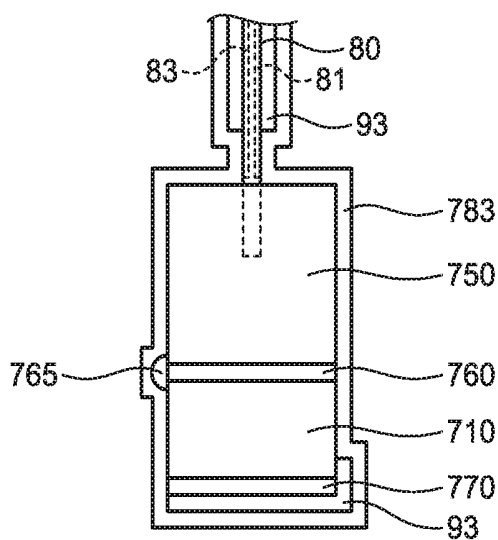


FIG.30

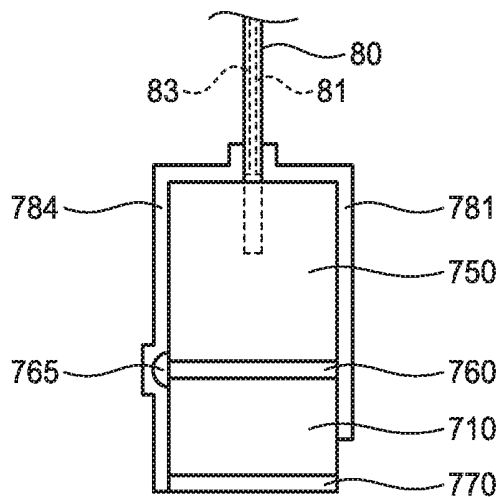


FIG.31

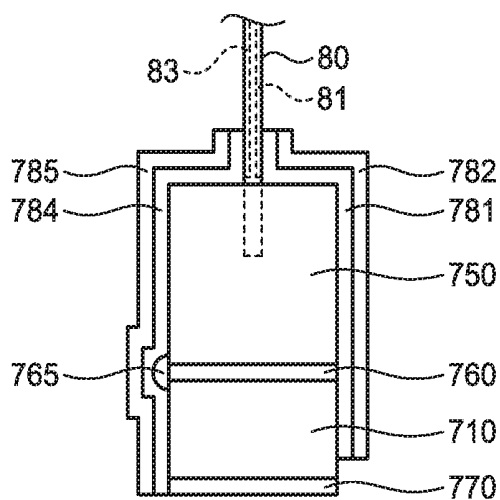
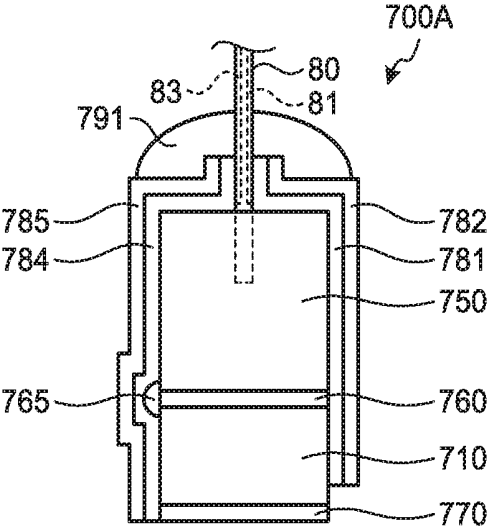


FIG.32



**ULTRASOUND TRANSDUCER,
ULTRASOUND PROBE AND METHOD OF
MANUFACTURING ULTRASOUND
TRANSDUCER**

CROSS-REFERENCE TO RELATED
APPLICATIONS

[0001] This application is a continuation of PCT international application Ser. No. PCT/JP2016/061046 filed on Apr. 4, 2016 which designates the United States, incorporated herein by reference, and which claims the benefit of priority from Japanese Patent Application No. 2015-086781, filed on Apr. 21, 2015, incorporated herein by reference.

BACKGROUND

1. Technical Field

[0002] The disclosure relates to an ultrasound transducer, an ultrasound probe and a method of manufacturing an ultrasound transducer.

2. Related Art

[0003] Ultrasound is applied in some cases for observing a characteristic of a living tissue or material as an observation target. Specifically, the ultrasound transducer transmits ultrasound to the observation target, receives an ultrasound echo reflected by the observation target, and an ultrasound observation apparatus performs predetermined signal processing on the received ultrasound echo, whereby information related to the characteristic of the observation target can be obtained.

[0004] The ultrasound transducer includes a plurality of piezoelectric elements that converts an electrical pulse signal into an ultrasound pulse (acoustic pulse), emits the ultrasound pulse to the observation target, converts an ultrasound echo reflected on the observation target into an electrical echo signal expressed by a voltage change, and outputs the echo signal (refer to JP 2002-224104 A, for example). The ultrasound echo is obtained from the observation target, for example, by arranging the plurality of piezoelectric elements in an array pattern, electronically switching the elements related to transmission and reception, or delaying transmission and reception of the piezoelectric body of each of the ultrasound transducer.

[0005] Meanwhile, each of the piezoelectric elements is electrically connected by wiring to a circuit board configured to transmit a pulse signal and receive an echo signal. The piezoelectric element and the wiring are connected by soldering, for example, and the heat at the time of soldering might induce degradation of the characteristics of the piezoelectric element, in the form of depolarization, or the like.

[0006] As a technique for suppressing depolarization of the piezoelectric element, there is a disclosed technique of forming a conductive thin film for providing electrical connection to the circuit board on a side surface of a base material forming the piezoelectric element and then dividing the base material after formation of the thin film so as to be able to electrically connect a plurality of piezoelectric elements with a circuit board without soldering (for example, refer to JP 2007-201901 A).

SUMMARY

[0007] In some embodiments, an ultrasound transducer includes: a plurality of piezoelectric elements configured to emit ultrasound according to an input of an electric signal and to convert ultrasound incident from outside into an electric signal; a substrate configured to perform input and output of an electric signal with respect to each of the piezoelectric elements; a plurality of signal input and output electrodes where each signal input and output electrode is provided between each piezoelectric element and the substrate and is configured to electrically connect the piezoelectric element with the substrate; a plurality of first backing materials where each first backing material is provided at each of the piezoelectric elements on a side where the signal input and output electrode is arranged and is configured to attenuate ultrasound vibration generated by operation of the piezoelectric element; a plurality of sealing portions where each sealing portion is configured to seal an outer surface of at least a portion of an electrical path connecting the substrate with the signal input and output electrode; a wall configured to surround a plurality of oscillating portions including the piezoelectric element, the first backing material, the signal input and output electrode, and the sealing portion; and a second backing material provided in a hollow space formed by the wall and the plurality of oscillating portions, and configured to attenuate the ultrasound vibration. The plurality of piezoelectric elements, the plurality of first backing materials, a portion of the substrate, the plurality of signal input and output electrodes, and the plurality of sealing portions are obtained by dividing a forming member along a stacking direction of the forming member, the forming member being formed by stacking a plurality of materials, each of the plurality of materials forming the piezoelectric elements, the first backing materials, the substrate, the signal input and output electrodes, and the sealing portions.

[0008] In some embodiments, a method of manufacturing an ultrasound transducer includes: a stacked member production process of stacking a plurality of materials to produce a stacked member, each of the materials forming: a plurality of piezoelectric elements configured to emit ultrasound according to an input of an electric signal and to convert ultrasound incident from outside into an electric signal; a portion of a substrate configured to perform input and output of an electric signal with respect to each of the piezoelectric elements; a plurality of signal input and output electrodes where each signal input and output electrode is provided between each piezoelectric element and the substrate and is configured to electrically connect the piezoelectric element with the substrate; and a plurality of first backing materials where each first backing material is provided at each of the piezoelectric elements on a side where the signal input and output electrode is arranged and is configured to attenuate ultrasound vibration generated by operation of the piezoelectric element; a forming member production process of sealing, with respect to the stacked member, an outer surface of at least a portion of an electrical path connecting the substrate with the signal input and output electrode to produce a forming member; a forming process of dividing the produced forming member produced by the forming member production process along a stacking direction of the forming member to form the piezoelectric element, the first backing material, a portion of the substrate, the signal input and output electrode, and sealing portion; a

wall arrangement process of arranging a wall surrounding a plurality of oscillating portions including the formed piezoelectric element, the formed first backing material, the formed signal input and output electrode, and the formed sealing portion, which are formed by the forming process; and a filling process of filling a second backing material in a hollow space formed by the wall and the plurality of oscillating portions.

[0009] The above and other features, advantages and technical and industrial significance of this disclosure will be better understood by reading the following detailed description of presently preferred embodiments of the disclosure, when considered in connection with the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

[0010] FIG. 1 is a diagram schematically illustrating an endoscope system according to a first embodiment of the disclosure;

[0011] FIG. 2 is a perspective view illustrating an ultrasound transducer according to the first embodiment of the disclosure;

[0012] FIG. 3 is a schematic diagram illustrating a configuration of a main portion of the ultrasound transducer according to the first embodiment of the disclosure;

[0013] FIG. 4 is a schematic diagram illustrating a configuration of a main portion of the ultrasound transducer according to the first embodiment of the disclosure;

[0014] FIG. 5 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the first embodiment of the disclosure;

[0015] FIG. 6 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the first embodiment of the disclosure;

[0016] FIG. 7 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the first embodiment of the disclosure;

[0017] FIG. 8 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the first embodiment of the disclosure;

[0018] FIG. 9 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the first embodiment of the disclosure;

[0019] FIG. 10 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the first embodiment of the disclosure;

[0020] FIG. 11 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the first embodiment of the disclosure;

[0021] FIG. 12 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the first embodiment of the disclosure;

[0022] FIG. 13 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a first modification of the first embodiment of the disclosure;

[0023] FIG. 14 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a second modification of the first embodiment of the disclosure;

[0024] FIG. 15 is a schematic diagram illustrating a production of a forming member of the ultrasound transducer according to the second modification of the first embodiment of the disclosure;

[0025] FIG. 16 is a schematic diagram illustrating a production of the forming member of the ultrasound transducer according to the second modification of the first embodiment of the disclosure;

[0026] FIG. 17 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a third modification of the first embodiment of the disclosure;

[0027] FIG. 18 is a schematic diagram illustrating a production of a forming member of the ultrasound transducer according to the third modification of the first embodiment of the disclosure;

[0028] FIG. 19 is a schematic diagram illustrating a configuration of a main portion of an ultrasound transducer according to a fourth modification of the first embodiment of the disclosure;

[0029] FIG. 20 is a schematic diagram illustrating a configuration of a main portion of an ultrasound transducer according to a fifth modification of the first embodiment of the disclosure;

[0030] FIG. 21 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a sixth modification of the first embodiment of the disclosure;

[0031] FIG. 22 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a seventh modification of the first embodiment of the disclosure;

[0032] FIG. 23 is a schematic diagram illustrating a configuration of an ultrasound transducer according to an eighth modification of the first embodiment of the disclosure;

[0033] FIG. 24 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a ninth modification of the first embodiment of the disclosure;

[0034] FIG. 25 is a diagram illustrating a method of manufacturing an ultrasound transducer according to a tenth modification of the first embodiment of the disclosure;

[0035] FIG. 26 is a schematic diagram illustrating a configuration of the ultrasound transducer according to the tenth modification of the first embodiment of the disclosure;

[0036] FIG. 27 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a second embodiment of the disclosure;

[0037] FIG. 28 is a diagram illustrating a method of manufacturing the ultrasound transducer according to the second embodiment of the disclosure;

[0038] FIG. 29 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the second embodiment of the disclosure;

[0039] FIG. 30 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the second embodiment of the disclosure;

[0040] FIG. 31 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the second embodiment of the disclosure; and

[0041] FIG. 32 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer according to the second embodiment of the disclosure.

DETAILED DESCRIPTION

[0042] Hereinafter, embodiments of the disclosure (hereinafter, referred to as embodiment(s)) will be described with reference to the drawings. Note that the disclosure is not limited by the following embodiments. In the drawings, same reference signs are attached to the same portions.

First Embodiment

[0043] FIG. 1 is a diagram schematically illustrating an endoscope system 1 according to a first embodiment of the disclosure. The endoscope system 1 is a system for performing ultrasound diagnosis of internal portions of a subject such as a human using an ultrasound endoscope. As illustrated in FIG. 1, the endoscope system 1 includes an ultrasound endoscope 2, an ultrasound observation apparatus 3, an endoscopic examination apparatus 4, a display device 5, and a light source apparatus 6.

[0044] The ultrasound endoscope 2, using its distal end portion, converts an electrical pulse signal received from the ultrasound observation apparatus 3 into an ultrasound pulse (acoustic pulse) and emits it to the subject, and also converts an ultrasound echo reflected on the subject into an electrical echo signal expressed by a voltage change and outputs the signal.

[0045] The ultrasound endoscope 2 typically includes imaging optics and imaging elements. The ultrasound endoscope 2 can be inserted into gastrointestinal tracts (esophagus, stomach, duodenum, and large intestine) or respiratory organs (trachea, bronchus) of the subject and can capture gastrointestinal tract, respiratory organs, and their surrounding organs (pancreas, gall bladder, bile duct, biliary tract, lymph nodes, mediastinal organs, blood vessels, or the like). The ultrasound endoscope 2 includes a light guide that guides illumination light emitted to the subject at the time of imaging. The light guide is configured such that a distal end portion thereof reaches a distal end of an insertion unit of the ultrasound endoscope 2 into the subject, while a proximal end portion thereof is connected to the light source apparatus 6 that generates illumination light.

[0046] As illustrated in FIG. 1, the ultrasound endoscope 2 includes an insertion unit 21, an operating unit 22, a universal cable 23, and a connector 24. The insertion unit 21 is a portion to be inserted into the subject. As illustrated in FIG. 1, the insertion unit 21 includes an ultrasound transducer 7, a rigid member 211, a bending portion 212, and a flexible tube portion 213. The ultrasound transducer 7 is provided at a distal end side of the insertion unit. The rigid member 211 is coupled to a proximal end side of the ultrasound transducer 7. The bending portion 212 is a bendable portion coupled to the proximal end side of the rigid member 211. The flexible tube portion 213 is a flexible portion coupled to the proximal end side of the bending portion 212. While specific illustration is omitted herein, the insertion unit 21 internally includes a light guide for transmitting illumination light supplied from the light source apparatus 6, a plurality of signal cables for transmitting various signals, and a treatment instrument insertion passage for inserting treatment instruments.

[0047] The ultrasound transducer 7 may be any of a convex transducer, a linear transducer, and a radial transducer. The ultrasound endoscope 2 may be configured to cause the ultrasound transducer 7 to perform mechanical scan, or may provide, as the ultrasound transducer 7, a plurality of piezoelectric elements in an array pattern, and may cause the ultrasound transducer 7 to perform electronic scan by electronically switching the piezoelectric elements related to transmission and reception or by imposing delay onto transmission and reception of each of the piezoelectric elements. The configuration of the piezoelectric element will be described below.

[0048] The operating unit 22 is coupled to the proximal end side of the insertion unit 21 and receives various types of operation from a doctor, or the like. As illustrated in FIG. 1, the operating unit 22 includes a bending knob 221 for performing bending operation on the bending portion 212, and a plurality of operating members 222 for performing various types of operation. Moreover, the operating unit 22 has a treatment instrument insertion port 223 communicating with the treatment instrument insertion passage formed inside the insertion unit 21 and used for inserting treatment instruments into the treatment instrument insertion passage.

[0049] Extending from the operating unit 22, the universal cable 23 includes a plurality of signal cables for transmitting various signals and an optical fiber for transmitting illumination light supplied from the light source apparatus 6.

[0050] The connector 24 is provided at the distal end of the universal cable 23. The connector 24 includes first to third connector units 241 to 243 each of which is connected with an ultrasound cable 31, a video cable 41, and an optical fiber cable 61, respectively.

[0051] The ultrasound observation apparatus 3 is electrically connected with the ultrasound endoscope 2 via the ultrasound cable 31, outputs a pulse signal to the ultrasound endoscope 2 via the ultrasound cable 31, while inputting echo signals from the ultrasound endoscope 2. Then, the ultrasound observation apparatus 3 performs predetermined processing on the echo signal and generates an ultrasound image.

[0052] The endoscopic examination apparatus 4 is electrically connected with the ultrasound endoscope 2 via the video cable 41, and inputs an image signal from the ultrasound endoscope 2 via the video cable 41. Then, the endoscopic examination apparatus 4 performs predetermined processing on the image signal and generates an endoscopic image.

[0053] The display device 5 is formed with liquid crystal, organic electroluminescence (EL), or the like, and displays an ultrasound image generated by the ultrasound observation apparatus 3, an endoscopic image generated by the endoscopic examination apparatus 4, or the like.

[0054] The light source apparatus 6 is connected with the ultrasound endoscope 2 via the optical fiber cable 61 and supplies illumination light for illuminating portions inside the subject, to the ultrasound endoscope 2 via the optical fiber cable 61.

[0055] Subsequently, the configuration of the ultrasound transducer 7 will be described with reference to FIGS. 2 to 4. FIG. 2 is a perspective view illustrating the ultrasound transducer 7 according to the first embodiment. FIG. 3 is a schematic diagram illustrating a configuration of a main portion of the ultrasound transducer 7 according to the first embodiment, illustrated as a plan view in the direction of arrow A in FIG. 3, in an upside down view of FIG. 3. While FIG. 4 illustrates an exemplary case where ten elements 70 including the piezoelectric elements 71 are arranged for simplicity of explanation, the configuration of the ultrasound transducer 7 is not limited to this number in actual arrangement. The first embodiment is described as an exemplary case where the ultrasound transducer 7 is a convex ultrasound transducer as illustrated in FIG. 2 including a one-dimensional array (1D array) of the plurality of piezoelectric elements 71 which is arranged in a

line. In other words, in the ultrasound transducer 7 according to the first embodiment, the plurality of elements 70 is arranged along an outer surface forming a curved surface of the ultrasound transducer 7.

[0056] As illustrated in FIGS. 3 and 4, the ultrasound transducer 7 includes the plurality of piezoelectric elements 71, a first acoustic matching layer 72 provided on an outer surface side of the ultrasound transducer 7 with respect to the piezoelectric elements 71, a second acoustic matching layer 73 provided on the side of the first acoustic matching layer 72 opposite to the side coming in contact with the piezoelectric element 71, an acoustic lens 74 provided on the side of the second acoustic matching layer 73 opposite to the side coming in contact with the first acoustic matching layer 72, a backing material 75 provided on the side of the piezoelectric element 71 opposite to the side coming in contact with the first acoustic matching layer 72, a first electrode 76 (signal input and output electrode) provided on a main surface of the piezoelectric element 71 on the backing material 75 side, a second electrode 77 provided on the main surface of the piezoelectric element 71 on the first acoustic matching layer 72 side, a conductive thin film 78 (connecting electrode) electrically connecting the first electrode 76 with a wiring pattern on an flexible printed circuit (FPC) substrate 80 to be described below, a sealing portion 79 for sealing a connecting portion between the conductive thin film 78 and the FPC substrate 80, and the FPC substrate 80 configured to perform input and output of electric signals on each of the piezoelectric elements 71. Note that the first embodiment has a configuration in which the first acoustic matching layer 72 and the backing material 75 are provided for each of the piezoelectric elements 71, and at the same time, the second acoustic matching layer 73 and the acoustic lens 74 integrally cover the plurality of piezoelectric elements 71 and the first acoustic matching layers 72. The element 70 in the first embodiment refers to an output unit including the piezoelectric element 71, the backing material 75, the first electrode 76, and the second electrode 77, and configured to output one ultrasound pulse according to a certain pulse signal. The first embodiment describes a case where one piezoelectric element 71 is an output unit. In a case, however, where ultrasound is simultaneously emitted from the plurality of piezoelectric elements 71 by a wiring pattern formed on the FPC substrate 80, a plurality of target piezoelectric elements 71 constitutes one element as an output unit.

[0057] The piezoelectric element 71 converts an electrical pulse signal into an ultrasound pulse (acoustic pulse), emits the ultrasound pulse to the subject, converts an ultrasound echo reflected on the subject into an electrical echo signal represented by a voltage change, and outputs the echo signal.

[0058] The piezoelectric element 71 is electrically connected with the FPC substrate 80 via the first electrode 76 by the conductive thin film 78. Each of the first electrode 76 and the second electrode 77 is formed of a metal material or a resin material, having conductivity.

[0059] The piezoelectric element 71 is formed with a PMN-PT single crystal, PMN-PZT single crystal, PZN-PT single crystal, PIN-PZN-PT single crystal, or a relaxer-based material. The PMN-PT single crystal is an abbreviation of a solid solution of lead magnesium niobate and lead titanate. The PMN-PZT single crystal is an abbreviation of a solid solution of lead magnesium niobate and lead zirconate

titanate. The PZN-PT single crystal is an abbreviation of a solid solution of lead zinc-niobate and lead titanate. The PIN-PZN-PT single crystal is an abbreviation of a solid solution of lead indium niobate, lead zinc-niobate, and lead titanate. The relaxer-based material is a general term of a three-component piezoelectric material obtained by adding lead-based complex perovskite as a relaxer material to the lead zirconate titanate (PZT) for the purpose of increasing the piezoelectric constant and dielectric constant. The lead-based complex perovskite is represented by $Pb(B1, B2)O_3$, in which B1 is any of magnesium, zinc, indium, and scandium, while B2 is any of niobium, tantalum, and tungsten. These materials have excellent piezoelectric effects. These materials could reduce the value of the electrical impedance even in a miniaturized form, and thus, would be preferable from the viewpoint of impedance matching with a thin film electrode.

[0060] In order to allow the sound (ultrasound) to be efficiently transmitted between the piezoelectric element 71 and the observation target, the first acoustic matching layer 72 and the second acoustic matching layer 73 perform matching of acoustic impedance between the piezoelectric element 71 and the observation target. The first acoustic matching layer 72 and the second acoustic matching layer 73 are formed of mutually different materials. Note that while the first embodiment describes a case where there are two acoustic matching layers (first acoustic matching layer 72 and second acoustic matching layer 73), it is also allowable to have one layer or three layers or more, in accordance with characteristics of the piezoelectric element 71 and the observation target. Moreover, as for the acoustic matching layer, it is allowable to configure as an ultrasound transducer that does not include the acoustic matching layer as long as the acoustic impedance matching with the observation target can be achieved.

[0061] The acoustic lens 74 is formed with polymethylpentene, epoxy resin, polyetherimide, or the like, and has a function of narrowing the ultrasound with one side having a concave shape. Note that the material may be a material whose sound speed is slower than the sound speed of the subject, such as a silicone resin, with a convex surface that allows the ultrasound beam to converge. Whether to provide the acoustic lens 74 may be optional, and thus, it is allowable to have a configuration without the acoustic lens 74.

[0062] The backing material 75 attenuates unneeded ultrasound vibration generated by operation of the piezoelectric element 71. The backing material 75 is formed of a material having a high attenuation rate, for example, epoxy resin in which a filler such as alumina and zirconia is dispersed, or formed of a rubber in which the above-described filler is dispersed.

[0063] The first electrode 76 is electrically connected with the FPC substrate 80 via the above-described conductive thin film 78. The first electrode 76 is an electrode for inputting and outputting a signal with respect to the piezoelectric element 71.

[0064] The second electrode 77 is formed in the first acoustic matching layer 72 and is electrically connected to a ground electrode 72a grounded to the ground potential.

[0065] The conductive thin film 78 forms an electrical conduction path between the first electrode 76 and the FPC substrate 80. The conductive thin film 78 is a conductive thin film formed on a side surface of the piezoelectric element 71 by a physical vapor deposition (PVD) method such as

sputtering and wet plating such as electrolytic plating, and configured to electrically connect the first electrode 76 with the wiring pattern formed on the FPC substrate 80. The conductive thin film 78 is obtained by forming a plating film on a stacked film formed of any of chromium/copper, chromium/gold, nickel-chromium/copper and chromium/copper/nickel.

[0066] The sealing portion 79 is formed with an insulating resin material and seals an outer surface of a portion of the backing material 75, and an outer surface of a portion of the FPC substrate 80 and the conductive thin film 78 including the connecting portion between the FPC substrate 80 and the conductive thin film 78.

[0067] The FPC substrate 80 is a substrate obtained by forming a wiring pattern formed of a conductive metal such as a copper foil on an insulating and flexible film-like base material formed of polyimide, or the like.

[0068] The piezoelectric element 71 vibrates with the input of the pulse signal, whereby the above-configured ultrasound transducer 7 emits ultrasound to the observation target via the first acoustic matching layer 72, the second acoustic matching layer 73, and the acoustic lens 74. At this time, the piezoelectric element 71 is configured such that the backing material 75 attenuates vibration of the piezoelectric element 71 on the side opposite to the arrangement side of the first acoustic matching layer 72, the second acoustic matching layer 73, and the acoustic lens 74, thereby suppressing transmission of vibration of the piezoelectric element 71 to the FPC substrate 80, or the like. Moreover, the ultrasound reflected from the observation target is transmitted to the piezoelectric element 71 via the first acoustic matching layer 72, the second acoustic matching layer 73, and the acoustic lens 74. The transmitted ultrasound causes the piezoelectric element 71 to vibrate, then, the piezoelectric element 71 converts the vibration into an electrical echo signal, and outputs the converted signal, as an echo signal, to the FPC substrate 80 via the conductive thin film 78.

[0069] Subsequently, a method of manufacturing the above-described ultrasound transducer 7 will be described with reference to FIGS. 5 to 12. FIGS. 5 to 10 are schematic diagrams illustrating a method of manufacturing the ultrasound transducer 7 according to the first embodiment. First, processing of producing a forming member (forming member 700 to be described below) for forming the piezoelectric element 71, the backing material 75, the first electrode 76, and the second electrode 77 will be described.

[0070] A first thin film 760 formed with a material forming the first electrode 76 and a second thin film 770 formed with a material forming the second electrode 77 are stacked on opposing main surfaces of a rectangular parallelepiped shaped piezoelectric element base material 710 formed with a material forming the piezoelectric element 71, and thereafter, a backing material base material 750 formed with a material forming the backing material 75 is stacked on the side of the first thin film 760 opposite to the piezoelectric element base material 710 side (refer to FIG. 5: stacked member production process). The backing material base material 750 is stacked while a portion of the FPC substrate 80 is embedded in the backing material base material 750.

[0071] Thereafter, a masking material 90 to cover the second thin film 770 and a portion of the FPC substrate 80 is arranged (refer to FIG. 6). The masking material 90 may be anything as long as it masks the second thin film 770 and a portion of the FPC substrate 80 in a region where film

forming is performed by sputtering to be described below. With this processing, film forming on the second thin film 770 by sputtering is prevented.

[0072] After the masking material 90 is arranged, a third thin film 781 is formed by sputtering using a material forming a portion of the conductive thin film 78 (refer to FIG. 7). Here, the third thin film 781 may include formation of gold (Au) with a thickness of 300 nm on an underlying layer of chromium (Cr) with a thickness of 50 nm, and include, on an underlying layer of nickel chromium (NiCr) with a thickness of 50 nm, stacks of copper (Cu) with a thickness of 100 nm and platinum (Pt) with a thickness of 400 nm, making it possible to form a conductive thin film with good adhesion. As a film forming method other than sputtering, silver (Ag) with a thickness of 1000 nm or silver palladium (AgPd) with a thickness of 700 nm may be formed by vapor deposition. By forming the third thin film 781, the first thin film 760 can be electrically connected with the wiring pattern formed on the FPC substrate 80.

[0073] After the third thin film 781 is formed, the masking material 90 is removed (refer to FIG. 8), and then, a plating film 782 is formed by electrolytic plating treatment (refer to FIG. 9). A stacked film (connecting member) forming the conductive thin film 78 is formed by the third thin film 781 and the plating film 782 (connection electrode member arrangement process). Materials applicable as the plating film 782 is materials forming a portion of the conductive thin film 78 formed by a sulfamic acid bath or a pyrophosphoric acid bath, such as nickel and copper. With the electrolytic plating treatment, the third thin film 781 is covered with the plating film 782. In physical vapor deposition, it used to be difficult to increase the film thickness to lower the resistance due to an issue of film stress. More specifically, when the film stress is high, the film peels off during cutting by a precision cutting machine such as a dicing saw, making it difficult to form a thick film. In contrast, film stress can be controlled on the plating of nickel sulfamate or copper pyrophosphate, making it possible to form a thick film of 1 to 10 μm , and to ensure the thickness of the conductive film necessary as the wiring to the transducer. In other words, by using the plating film 782, it is possible to enhance physical characteristics such as the strength and the electrical characteristics of the conductive thin film 78. A stacked member is produced by the above-described processing, and a series of processing corresponds to the stacked member production process of the disclosure.

[0074] After formation of the plating film 782, a sealing member 790 is provided on a surface of the backing material base material 750, in which the FPC substrate 80 is embedded, so as to seal the outer surfaces of a portion of the FPC substrate 80 including the contact portion between the FPC substrate 80 and the third thin film 781, a portion of the third thin film 781, and a portion of the plating film 782, with the sealing member 790 (refer to FIG. 10: forming member production process). The forming member 700 is produced with the above-described processing.

[0075] FIG. 11 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer 7 according to the first embodiment, viewed from the FPC substrate 80 side in FIG. 10. FIG. 11 is a top view illustrating a state in which a first acoustic matching layer base material 720 formed by stacking the second acoustic matching layer 73 is arranged on the second thin film 770 of the forming member 700 produced by the above-described processing,

with the first acoustic matching layer base material **720** being mounted on a machining tool **101**. The first acoustic matching layer base material **720** is formed of a material forming the first acoustic matching layer **72**.

[0076] The FPC substrate **80** includes a foil-shaped solid portion **81** formed of a conductive material for forming wiring patterns and uniformly extending to a portion of the surface of the FPC substrate **80**, and includes a pattern portion **82** in which a plurality of wiring lines **82a** extend from the solid portion **81** in accordance with the individual wiring patterns. The solid portion **81** and the pattern portion **82** are formed of copper, for example. The above-described third thin film **781** is in contact with the solid portion **81**.

[0077] The FPC substrate **80** is positioned on the machining tool **101** by a positioning pin **91**. At this time, the height of an end portion of the solid portion **81** connected to the pattern portion **82** is adjusted by a height adjusting member **M** (refer to FIG. 12) formed of machinable ceramics, or the like. Herein, the height is adjusted to the height at which a plane passing through the front surface of the FPC substrate **80**, that is, the front surface coming in contact with the height adjusting member **M**, passes through the first acoustic matching layer base material **720**.

[0078] FIG. 12 is a schematic diagram illustrating a method of manufacturing the ultrasound transducer **7** according to the first embodiment, as a side view from the arrangement direction of the individual wiring lines **82a** of the pattern portion **82** in FIG. 11. As illustrated in FIG. 12, after arrangement of the FPC substrate **80**, the forming member **700** connected to the FPC substrate **80**, and the first acoustic matching layer base material **720** arranged on the forming member **700** and on which the second acoustic matching layer **73** is arranged, on the machining tool **101**, cutting is performed on a portion of the FPC substrate **80** including the solid portion **81**, the forming member **700**, and the first acoustic matching layer base material **720** using a dicing saw **100**. Specifically, as illustrated in FIGS. 11 and 12, by rotating and moving a blade of a precision cutting machine such as the dicing saw **100** along a cutting path **C1** passing through the portions between the wiring lines **82a** of the pattern portion **82** and extending in the longitudinal direction of the FPC substrate **80**, a portion of the FPC substrate **80**, the forming member **700**, and the first acoustic matching layer base material **720** are cut and divided along a stacking direction of the forming member **700** (forming process). Note that the stacking direction herein refers to a stacking direction of the piezoelectric element base material **710**, the first thin film **760**, the second thin film **770**, and the backing material base material **750**. The solid portion **81** is divided by the dicing saw **100** in accordance with each of the wiring lines **82a** and at the same time, the piezoelectric element **71**, the first acoustic matching layer **72**, the backing material **75**, the first electrode **76**, the second electrode **77**, the conductive thin film **78** and the sealing portion **79** are formed, and thereafter, by arranging the acoustic lens **74**, the ultrasound transducer **7** illustrated in FIGS. 3 and 4 is obtained.

[0079] The piezoelectric element **71** is formed by dividing the piezoelectric element base material **710** by the dicing saw **100**. In this case, the piezoelectric element **71** has a rectangular parallelepiped shape, and when a length in the arrangement direction of the plurality of piezoelectric elements **71** in a plane orthogonal to the cut surface is w , and a length in the stacking direction of the first acoustic

matching layer **72**, or the like, orthogonal to the arrangement direction is t , it is preferable that a ratio represented by w/t is 0.3 to 0.7 in that this would achieve high electricity-machine conversion efficiency.

[0080] As described above, the first embodiment is a case of forming the forming member **700** including the piezoelectric element base material **710**, the backing material base material **750**, the first thin film **760**, the second thin film **770**, and the third thin film **781**. The forming member **700** has a portion of the FPC substrate **80** including a contact portion between the FPC substrate **80** and the third thin film **781**, a portion of the third thin film **781**, and a portion of the plating film **782** being sealed with the sealing member **790**, and thereafter, the forming member **700** is cut in accordance with the wiring line **82a** together with the FPC substrate **80** including the solid portion **81**. Since the piezoelectric element **71** and the FPC substrate **80** are electrically connected without using a bonding material that generates heat such as solder, it is possible to suppress degradation of the characteristics of the piezoelectric element **71** and to allow the space between the piezoelectric elements **71** to be about the thickness of the blade of the dicing saw **100**, or the like. With this configuration, it is possible to realize a narrow pitch of the plurality of piezoelectric elements.

[0081] Moreover, according to the above-described first embodiment, the plurality of piezoelectric elements **71** and the FPC substrate **80** are connected with each other merely by cutting and dividing the solid portion **81** using the dicing saw **100**. This configuration eliminates necessity of performing high-accuracy alignment of the piezoelectric element **71** and the wiring (for example, the wiring lines **82a**), making it possible to perform production easily even when the pitch between the piezoelectric elements **71** is fine. This enables production of a high-quality ultrasound transducer for which narrow pitch is demanded.

[0082] In the first embodiment described above, it is also allowable to fix a relative relationship between the forming member **700** and the FPC substrate **80** by filling wax or the like between the forming member **700** and the FPC substrate **80**.

[0083] While the above-described first embodiment is a case where the forming member **700** includes the piezoelectric element base material **710**, the backing material base material **750**, the first thin film **760**, the second thin film **770**, and the third thin film **781**, the forming member **700** may further include the first acoustic matching layer base material **720**, or the like.

First Modification of First Embodiment

[0084] FIG. 13 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a first modification of the first embodiment. While the above-described first embodiment is a case where the ultrasound transducer **7** includes one backing material (backing material **75**), the ultrasound transducer **7** includes two backing materials in the first modification. As illustrated in FIG. 13, in the configuration of the ultrasound transducer **7** described above, a wall **92** having a hollow rectangular prism shape is built at the first acoustic matching layer **72**, and a second backing material **75a** is filled in a hollow space formed by the wall **92**, thereby producing an ultrasound transducer **7a**. The wall **92** encloses a plurality of oscillating portions including the piezoelectric element **71**, the backing material **75**, the first electrode **76**, the second electrode **77**, the

conductive thin film 78, and the sealing portion 79. The second backing material 75a is provided in a hollow space formed by the wall 92 and the plurality of oscillating portions.

[0085] The acoustic impedance of the second backing material 75a is smaller than the acoustic impedance of the backing material 75 (first backing material). With application of the two backing materials having such a relationship, it is possible to cause the backing material 75 to hold the piezoelectric element 71 and to attenuate the unnecessary vibration with high efficiency, and to suppress transmission of vibration as a cause of crosstalk to the adjacent piezoelectric element 71 by the second backing material 75a. Therefore, according to the first modification, it is possible to realize reduction in the pulse width and suppression of crosstalk.

Second Modification of First Embodiment

[0086] FIG. 14 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a second modification of the first embodiment. While the above-described first embodiment is a case where the ultrasound transducer 7 includes the first electrode 76 having a flat plate shape, the second modification is a case where an ultrasound transducer 7b includes a thick portion 76a on the side of first electrode 76 coming in contact with the conductive thin film 78.

[0087] The thick portion 76a forms a portion of an electrical conduction path between the first electrode 76 and the FPC substrate 80. For example, the thick portion 76a is formed of the same conductive material as that of the first electrode 76, and comes in contact with the conductive thin film 78. FIGS. 15 and 16 are schematic diagrams illustrating production of a forming member of the ultrasound transducer according to the second modification of the first embodiment. As illustrated in FIG. 15, the forming member of the ultrasound transducer 7b according to the second modification is produced using a member having a structure in which a first thin film 762 having a plurality of protrusions 761 to be the thick portion 76a after the cutting processing is formed on one main surface of a piezoelectric element base material 711, while a second thin film 771 is formed on the other main surface of the piezoelectric element base material 711. Specifically, as illustrated in FIG. 16, after a backing material base material 751 is arranged on the first thin film 762, cutting is performed along a cutting path C2 passing through the protrusion 761, thereby obtaining a stacked body for forming the forming member including the piezoelectric element base material 710, the backing material base material 750, and the second thin film 770.

[0088] According to the second modification, by forming the thick portion 76a, the contact area between the first electrode 76 and the conductive thin film 78 is larger than the case of the first electrode 76 without the thick portion 76a described above, making it possible to provide further reliable electrical connection.

Third Modification of First Embodiment

[0089] FIG. 17 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a third modification of the first embodiment. While the above-described second modification is a case where the ultrasound transducer 7b includes the first electrode 76 having the thick

portion 76a, the third modification is a case where an ultrasound transducer 7c includes a first electrode 76b and a second electrode 77a being exposed on each of opposing side surfaces.

[0090] The first electrode 76b has the thick portion 76a on an arrangement side of the conductive thin film 78 and is continuous to the side surface of the piezoelectric element 71 on the arrangement side of the conductive thin film 78 to be exposed to the outside, while retreating relative to the side surface of the piezoelectric element 71 on the side opposite to the side coming in contact with the conductive thin film 78. Moreover, the second electrode 77a is continuous to the side surface of the piezoelectric element 71 on the side opposite to the arrangement side of the conductive thin film 78 to be exposed to the outside, while retreating relative to the side surface of the piezoelectric element 71 on the arrangement side of the conductive thin film 78.

[0091] FIG. 18 is a schematic diagram illustrating production of a forming member of the ultrasound transducer according to the third modification of the first embodiment. As illustrated in FIG. 18, the forming member of the ultrasound transducer 7c according to the third modification is produced using a member having a structure in which a plurality of first thin films 764 having a protrusion 763 to be the thick portion 76a is formed on one main surface of the piezoelectric element base material 711, while a plurality of second thin films 772 is formed on the other main surface of the piezoelectric element base material 711. The first thin film 764 and the second thin film 772 are arranged in an alternating manner when viewed from the thickness direction of the piezoelectric element base material 711, with a space (gap) between the second thin films 772 being located at a position opposing the protrusion 763. The backing material base material 751 is arranged on the first thin film 764 having the protrusion 763, and thereafter, cutting is performed along a cutting path C3 passing through the protrusion 763, thereby obtaining a stacked body for forming the forming member.

Fourth Modification of First Embodiment

[0092] FIG. 19 is a schematic diagram illustrating a configuration of a main portion of an ultrasound transducer according to a fourth modification of the first embodiment. While the above-described first embodiment is a case of the ultrasound transducer 7 in which a slit formed by cutting has a uniform width, the slit may be formed substantially in a V-shape having its width increasing toward the FPC substrate 80 side as in the fourth modification. According to the fourth modification, by widening a groove width on the FPC substrate 80 side, it is possible to facilitate casting operation of the second backing material after the cut stacked body is bent at the time of producing a convex transducer or a radial transducer.

Fifth Modification of First Embodiment

[0093] FIG. 20 is a schematic diagram illustrating a configuration of a main portion of an ultrasound transducer according to a fifth modification of the first embodiment. While the above-described first embodiment is a case of the ultrasound transducer 7 in which the slit formed by cutting has a uniform width, the slit may be formed in a stepped shape having its width increasing toward the FPC substrate 80 side as in the fifth modification.

Sixth Modification of First Embodiment

[0094] FIG. 21 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a sixth modification of the first embodiment, and is a diagram illustrating a configuration of a forming member. While the above-described first embodiment is a case where the backing material 75 has a prismatic shape, the backing material 75 may be a backing material 75*b* having a chamfered outer edge on the surface of the side holding the FPC substrate 80 as illustrated as an ultrasound transducer 7*d* according to the sixth modification. With this chamfering, it is possible to suppress damage on the conductive thin film 78.

Seventh Modification of First Embodiment

[0095] FIG. 22 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a seventh modification of the first embodiment, and is a diagram illustrating a configuration of a forming member. While the above-described first embodiment is a case where the backing material 75 has a prismatic shape, the backing material 75 may be a backing material 75*c* having a trapezoidal shape in side view with the width decreasing toward the side holding the FPC substrate 80 as illustrated as an ultrasound transducer 7*e* according to the seventh modification.

Eighth Modification of First Embodiment

[0096] FIG. 23 is a schematic diagram illustrating a configuration of an ultrasound transducer according to an eighth modification of the first embodiment and is a diagram illustrating a configuration of a forming member. While the above-described first embodiment is a case where the backing material 75 has a prismatic shape, the backing material 75 may be a backing material 75*d* having a curved surface on the side holding the FPC substrate 80 as illustrated as an ultrasound transducer 7*f* according to the eighth modification.

Ninth Modification of First Embodiment

[0097] FIG. 24 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a ninth modification of the first embodiment. While the above-described first embodiment is a case where the FPC substrate 80 is embedded in the backing material 75 and connected to the first electrode 76 via the conductive thin film 78, it is allowable to directly connect the first electrode 76 with the solid portion 81 after the division of the FPC substrate 80 by arranging the FPC substrate 80 on the side surface of the backing material 75 as in an ultrasound transducer 7*g* according to the ninth modification. In this case, a sealing portion 79*a* is formed at a connecting portion between the first electrode 76 and the FPC substrate 80.

[0098] Note that by applying the configuration of the ultrasound transducer 7*b* according to the above-described second modification also to the ninth modification, the contact region with the FPC substrate 80 is increased due to the thick portion 76*a*, making it possible to make the electrical connection further easy and stable.

Tenth Modification of First Embodiment

[0099] FIG. 25 is a diagram illustrating a method of manufacturing an ultrasound transducer according to a tenth modification of the first embodiment. FIG. 26 is a schematic

diagram illustrating a configuration of the ultrasound transducer according to the tenth modification of the first embodiment. While the above-described first embodiment is an exemplary case of using a 1D array, application is also possible to a 1.25D array, a 1.5D array, or a 1.75D array in which a plurality of piezoelectric elements (oscillating portions) is arranged in a direction (elevation direction) substantially orthogonal to the scanning direction (arrangement direction of piezoelectric elements in the 1D array, the arrangement direction of piezoelectric elements along which the forming member 700 is divided) of the ultrasound transducer. Note that in a convex ultrasound transducer, the plurality of piezoelectric elements (oscillating portions) is arranged in a direction along a spherical surface in the arrangement direction of the piezoelectric elements, that is, a direction perpendicular to the scanning direction. For example, with a method of manufacturing a 1.25D-array ultrasound transducer illustrated in FIG. 25, there are provided three forming members as described above, for example, a first forming member 701, a second forming member 702, and a third forming member 703, respectively connected to mutually different FPC substrates 80*a* to 80*c*. The forming members 701 to 703 are arranged in the moving direction of the dicing saw 100 and thereafter individually divided along a cutting path C4 using the dicing saw 100, thereby achieving production of a 1.25D-array ultrasound transducer 7*h* having elements 70*a* to 70*c* as illustrated in FIG. 26.

[0100] Alternatively, the 1.25D-array ultrasound transducer 7*h* illustrated in FIG. 26 may be formed by building a wall serving as a weir at the time of casting of the backing material as illustrated in the first modification (refer to FIG. 13), and then, casting a portion between the groove and the wall divided by the dicing saw 100 using a liquid backing material and solidifying the backing material, so as to obtain a 1.25D-array ultrasound transducer. Examples of the liquid backing material include liquid materials obtained by mixing alumina (Al₂O₃), zirconia (ZrO₂), or the like, as a filler, with epoxy resin or silicone resin that can maintain flexibility after being cured. This also applies to ultrasound transducers with 1.5D array and 1.75D array in a similar manner.

Second Embodiment

[0101] FIG. 27 is a schematic diagram illustrating a configuration of an ultrasound transducer according to a second embodiment. While the above-described first embodiment is a case where the second electrode 77 is connected to the ground electrode 72*a* provided in the first acoustic matching layer 72, the second embodiment is configured such that the second electrode 77 is electrically connected to a ground pattern 83 formed on the FPC substrate 80.

[0102] As illustrated in FIG. 27, an ultrasound transducer 7*i* according to the second embodiment includes a second conductive thin film 78*a* configured to connect the ground pattern 83 provided on a surface of the FPC substrate 80 opposite side of the connection surface of the conductive thin film 78 with the second electrode 77, in contrast with the above-described ultrasound transducer 7. Note that, in the second embodiment, the first acoustic matching layer 72 does not include the ground electrode 72*a*.

[0103] Next, a method of manufacturing the ultrasound transducer 7*i* will be described with reference to FIGS. 28 to 32. FIGS. 28 to 32 are schematic diagrams illustrating a

method of manufacturing the ultrasound transducer according to the second embodiment. Herein, production of a forming member for forming the piezoelectric element 71, the backing material 75, the first electrode 76, the second electrode 77, the conductive thin film 78 (first conductive thin film) and the second conductive thin film 78a will be described.

[0104] First, as described above, the first thin film 760 and the second thin film 770 are formed on opposing main surfaces of the piezoelectric element base material 710, and thereafter, backing material base material 750 is provided on a side opposite to the piezoelectric element base material 710 side of the first thin film 760 (refer to FIG. 5).

[0105] Thereafter, a masking material 93 to cover the second thin film 770 and a portion of the FPC substrate 80 is arranged and a thin film formation prevention member 765 configured to prevent thin film formation by sputtering is arranged on a side of the first thin film 760, the side opposite to the formation surface of the conductive thin film 78 (refer to FIG. 28). A fourth thin film 783 is formed by sputtering using the material of the stacked film, being one constituent material of the conductive thin film 78 and the second conductive thin film 78a (refer to FIG. 29).

[0106] After formation of the fourth thin film 783, the masking material 93 is removed (refer to FIG. 30), leading to a state where the fourth thin film 783 is divided into the third thin film 781 connecting the first thin film 760 with the wiring pattern formed on the FPC substrate 80, and a fifth thin film 784 connecting the second thin film 770 with the ground pattern formed on the FPC substrate 80. Thereafter, the plating film 782 covering the third thin film 781 and a second plating film 785 covering the fifth thin film 784 are formed by electroplating treatment (refer to FIG. 31).

[0107] After formation of the plating film 782 and the second plating film 785, a sealing member 791 is provided on a surface of the backing material base material 750, on which the FPC substrate 80 is embedded, so as to seal a portion of the FPC substrate 80 including the contact portion between the FPC substrate 80 and each of the third thin film 781 and the fifth thin film 784, a portion of the third thin film 781 and a portion the fifth thin film 784, and a portion of the plating film 782 and a portion of the second plating film 785, by the sealing member 791 (refer to FIG. 32). A forming member 700A is produced by the above-described processing.

[0108] Thereafter, similarly to the above-described processing, the first acoustic matching layer base material 720 on which the second acoustic matching layer 73 is stacked is arranged on the second thin film 770 of the forming member 700A, so as to be mounted on the machining tool 101, and then, by rotating and moving the dicing saw 100 along the cutting path C1 (refer to FIGS. 11 and 12) extending in the longitudinal direction of the FPC substrate 80, a portion of the FPC substrate 80, the forming member 700A, and the first acoustic matching layer base material 720 are cut. The solid portion 81 and the ground pattern 83 are cut by the dicing saw 100 according to each of the wiring lines 82a and at the same time, the piezoelectric element 71, the first acoustic matching layer 72, the backing material 75, the first electrode 76, the second electrode 77, the conductive thin film 78, the second conductive thin film 78a, and a sealing portion 79b are formed, and thereafter, the acoustic lens 74 is arranged, thereby obtaining the ultrasound transducer 7i illustrated in FIG. 27. Note that a second sealing

portion 76c formed by the thin film formation prevention member 765 is formed on the first electrode 76 on the second conductive thin film 78a side, thereby insulating between the first electrode 76 and the second conductive thin film 78a.

[0109] As described above, the second embodiment is a case of forming the forming member 700A including the piezoelectric element base material 710, the backing material base material 750, the first thin film 760, the second thin film 770, the fifth thin film 784, and the second plating film 785. The forming member 700A has a portion of the FPC substrate 80 including the contact portions between the FPC substrate 80 and each of the third thin film 781 and the fifth thin film 784, a portion of the third thin film 781 and a portion of the fifth thin film 784, and a portion of the plating film 782 and a portion of the second plating film 785 being sealed with the sealing member 791, and thereafter, the forming member 700A is cut in accordance with the wiring line 82a together with the FPC substrate 80 including the solid portion 81 and the ground pattern 83. Since the piezoelectric element 71 and the FPC substrate 80 are electrically connected without using a bonding material that generates heat such as solder, it is possible to suppress degradation of the characteristics of the piezoelectric element 71 and to allow the space between the piezoelectric elements 71 to be about the thickness of the blade of the dicing saw 100, or the like. With this configuration, it is possible to realize a narrow pitch of the plurality of piezoelectric elements.

[0110] Note that by applying the configuration of the ultrasound transducer 7c according to the third modification of the first embodiment described above also to the second embodiment, the backing material 75 (backing material base material 750) suppresses exposure of the side of the first electrode 76b opposite to the side coming in contact with the conductive thin film 78 to the outside. With this configuration, there is no need to provide the thin film formation prevention member 765, making it possible to produce an ultrasound transducer with the reduced number of components.

[0111] According to some embodiments, it is possible to suppress, in an ultrasound transducer, degradation of characteristics of the piezoelectric element in manufacture and to realize a narrow pitch in the plurality of piezoelectric elements.

[0112] Embodiments of the disclosure have been described hereinabove, however, the disclosure is not intended to be limited to the above-described embodiments and the modification example. The disclosure is not intended to be limited to the above-described embodiments and modification example but may include various forms of embodiments without deviating from the technical spirit and scope of the general inventive concept as defined in the appended claims of this application. Furthermore, the components described in each of the embodiments and modification examples may be appropriately combined with each other.

[0113] In this manner, the disclosure may include various forms of embodiments without deviating from the technical spirit and scope of the general inventive concept as defined in the appended claims of this application.

What is claimed is:

1. An ultrasound transducer comprising:
 - a plurality of piezoelectric elements configured to emit ultrasound according to an input of an electric signal and to convert ultrasound incident from outside into an electric signal;
 - a substrate configured to perform input and output of an electric signal with respect to each of the piezoelectric elements;
 - a plurality of signal input and output electrodes where each signal input and output electrode is provided between each piezoelectric element and the substrate and is configured to electrically connect the piezoelectric element with the substrate;
 - a plurality of first backing materials where each first backing material is provided at each of the piezoelectric elements on a side where the signal input and output electrode is arranged and is configured to attenuate ultrasound vibration generated by operation of the piezoelectric element;
 - a plurality of sealing portions where each sealing portion is configured to seal an outer surface of at least a portion of an electrical path connecting the substrate with the signal input and output electrode;
 - a wall configured to surround a plurality of oscillating portions including the piezoelectric element, the first backing material, the signal input and output electrode, and the sealing portion; and
 - a second backing material provided in a hollow space formed by the wall and the plurality of oscillating portions, and configured to attenuate the ultrasound vibration,
 wherein the plurality of piezoelectric elements, the plurality of first backing materials, a portion of the substrate, the plurality of signal input and output electrodes, and the plurality of sealing portions are obtained by dividing a forming member along a stacking direction of the forming member, the forming member being formed by stacking a plurality of materials, each of the plurality of materials forming the piezoelectric elements, the first backing materials, the substrate, the signal input and output electrodes, and the sealing portions.
2. The ultrasound transducer according to claim 1, wherein the signal input and output electrode includes a thick portion forming a portion of the electrical path.
3. The ultrasound transducer according to claim 1, comprising a connection electrode connected to each of the substrate and the signal input and output electrode, and configured to form the electrical path.
4. The ultrasound transducer according to claim 3, wherein a portion of the substrate is held by the first backing material, and
 - the connection electrode is connected to the substrate via a side surface of the first backing material.
5. The ultrasound transducer according to claim 3, wherein the connection electrode includes a thin film formed by a physical vapor deposition method and a plating film formed by wet plating.
6. The ultrasound transducer according to claim 4, wherein a portion of the substrate is embedded in the first backing material.
7. The ultrasound transducer according to claim 4, wherein a portion of the substrate is provided along a side surface of the first backing material.
8. The ultrasound transducer according to claim 1, further comprising:
 - a second electrode paired with the signal input and output electrode; and
 - an acoustic matching layer provided at the piezoelectric element on a side opposite to a side on which the first backing material is arranged and configured to adjust acoustic impedance of the ultrasound,
 wherein the second electrode is grounded to a ground potential via conductive resin provided between the acoustic matching layer and the piezoelectric element.
9. The ultrasound transducer according to claim 1, wherein the plurality of piezoelectric elements is arranged in a scanning direction along which the forming member is divided and in an elevation direction substantially orthogonal to the scanning direction.
10. An ultrasound probe comprising the ultrasound transducer according to claim 1 at a distal end of the ultrasound probe.
11. A method of manufacturing an ultrasound transducer comprising:
 - stacking a plurality of materials to produce a stacked member, each of the materials forming:
 - a plurality of piezoelectric elements configured to emit ultrasound according to an input of an electric signal and to convert ultrasound incident from outside into an electric signal;
 - a portion of a substrate configured to perform input and output of an electric signal with respect to each of the piezoelectric elements;
 - a plurality of signal input and output electrodes where each signal input and output electrode is provided between each piezoelectric element and the substrate and is configured to electrically connect the piezoelectric element with the substrate; and
 - a plurality of first backing materials where each first backing material is provided at each of the piezoelectric elements on a side where the signal input and output electrode is arranged and is configured to attenuate ultrasound vibration generated by operation of the piezoelectric element;
 - sealing, with respect to the stacked member, an outer surface of at least a portion of an electrical path connecting the substrate with the signal input and output electrode to produce a forming member;
 - dividing the produced forming member along a stacking direction of the forming member to form the piezoelectric element, the first backing material, a portion of the substrate, the signal input and output electrode, and sealing portion;
 - arranging a wall surrounding a plurality of oscillating portions including the formed piezoelectric element, the formed first backing material, the formed signal input and output electrode, and the formed sealing portion; and
 - a filling process of filling a second backing material in a hollow space formed by the wall and the plurality of oscillating portions.
12. The method of manufacturing an ultrasound transducer according to claim 11,

wherein the stacking of the materials includes arranging a connection electrode member for forming a connection electrode connected to each of the substrate and the signal input and output electrode, the connection electrode being configured to form the electrical path.

13. The method of manufacturing an ultrasound transducer according to claim **12**,

wherein the arranging of the connection electrode member includes:

forming a thin film on an outer surface corresponding to the electrical path by a physical vapor deposition method; and

forming a plating film on an outer surface of the thin film by wet plating.

14. The method of manufacturing an ultrasound transducer according to claim **11**,

wherein the forming member is obtained by stacking a material forming the piezoelectric element, a material forming the signal input and output electrode, and a material forming the first backing material in this order, and by causing the substrate to be held by the first backing material, and

the dividing of the produced forming member includes cutting the forming member such that a distance between adjacent members formed by division increases in a direction from the piezoelectric element toward the substrate.

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专利名称(译)	超声换能器，超声探头和制造超声换能器的方法		
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摘要(译)

超声换能器包括：压电元件；基板，其被构造为对每个压电元件执行电信号的输入和输出；信号输入和输出电极，其中每个信号输入和输出电极设置在每个压电元件和衬底之间；第一背衬材料，其中每个第一背衬材料设置在布置有信号输入和输出电极的一侧上的每个压电元件；密封部分，其中每个密封部分被配置为密封连接基板与信号输入和输出电极的电路径的至少一部分的外表面；围绕包括所述压电元件，所述第一背衬材料，所述信号输入和输出电极以及所述密封部分的振荡部分的壁；以及设置在由所述壁和所述振荡部分形成的中空空间中的第二背衬材料。

